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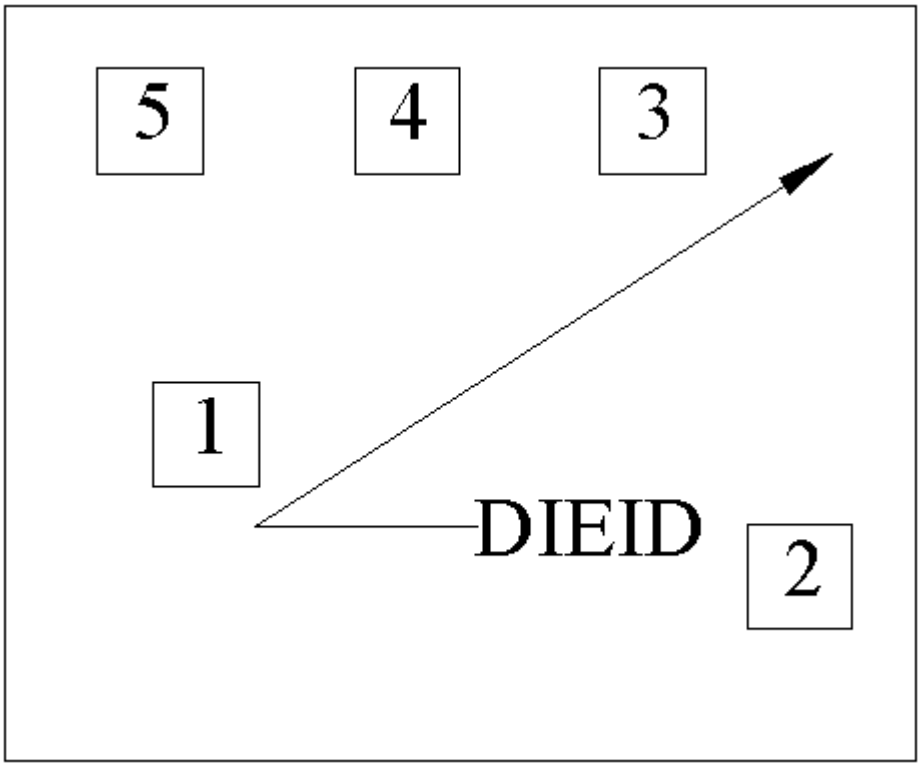
DPBU
Die Datasheet

LMH6723 MDC MCD2620A
SINGLE 370 MHZ 1 MA CURRENT FEEDBACK OP AMP

July 16,2007

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6723A	Bond Pad Opening Size (min)	92µm x 92µm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	795µm x 658µm 31.3mils x 25.9mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	214µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
Output	1	-222	-45	92	x	92
V +	2	296	-169	92	x	92
IN -	3	167	229	92	x	92
IN +	4	-47	229	92	x	92
V -	5	-271	229	92	x	92

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Notes

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